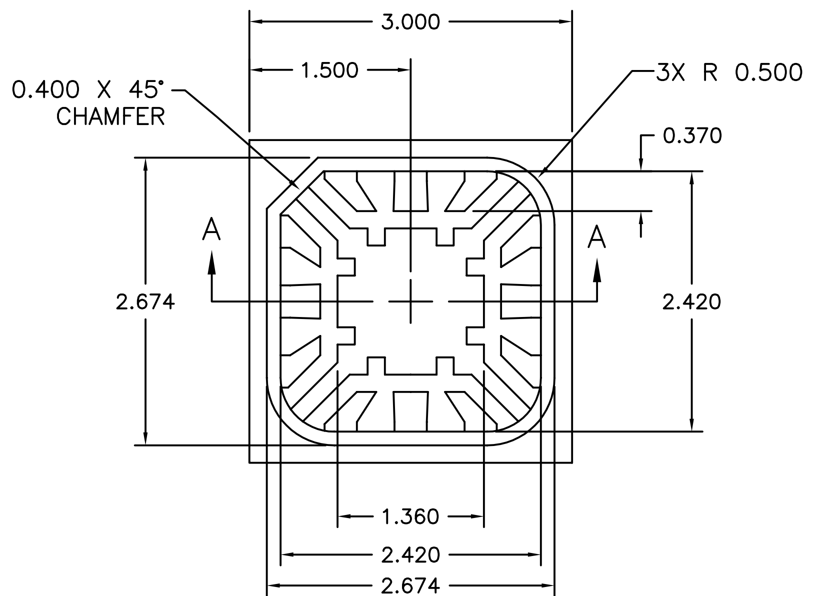
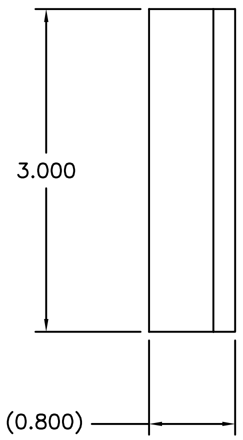
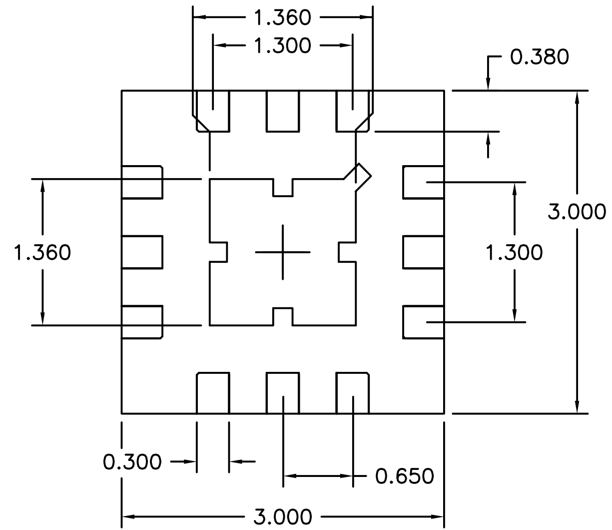
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10585	1/20/06	PRODUCTION RELEASE	D.BENANDO

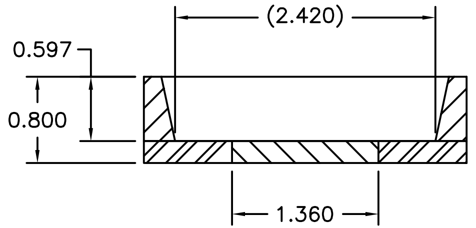


TOP VIEW



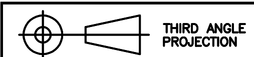


BOTTOM VIEW



SECTION A–A

NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076.
6. DIE PAD: 1.360mm X 1.360mm.
7. JEDEC OUTLINE: MO–220 (VEEC–1)



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
X.XX ± 0.015 X.XXXX ±–––
X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	1/20/06
APP BY	P. FLASKERUD	DATE	1/20/06
CUSTOMER	–––		

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12 Lead 3mm x 3mm MLP Open–Pak

SIZE	PART NO.	REV
A	MLP3X3–12–OP–01	1
SCALE NONE	CAD FILE MLP3X3–12–OP–01–R1.DWG	SHEET 1 OF 1

BORDER–BIN1.DWG
REV 1 ECN 10XXX